Introduction (4541.554 Introduction to Computer-Aided Design)

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Warming Up

- Königsberg Bridge Problem
 - Königsberg (Kaliningrad) bridges
 - Walk across each bridge exactly once



• Euler Trail

- Model it as a graph
- Euler trail: a trail that traverses all edges exactly once
- No more than 2 vertices must have odd degree







- Functional Cell Design
 - Layout
 - Layers: diffusion, metal, poly
 - Linear array of transistors
 - Avoid diffusion gaps to minimize area



- Functional Cell Design
 - How to minimize the number of diffusion gaps?
 - Find an Euler trail



Electronic Systems Design

• Embedded systems



• 3G Mobile Communication (CDMA2000)



Major Factors to be Considered

- Time-to-market
- Technology
- Performance
- Power consumption
- Reliability
- Testability
- Availability of CAD tools, libraries, IP's
- Cost, chip area
- ...

Time-to-Market

• Product life time vs. development time



• Revenue and time-to-market



Lost Revenue = Total Expected Revenue $\times \frac{d(3w - d)}{2w^2}$ w = 1 year, d = 4 months \rightarrow 40.5% lost

Technology

• Memory capacity quadrupled every three years





• Problems with deep sub-micron design

- Thin wire
 - Large interconnect delay
 - delay \propto (wire length)²
 - Al --> Cu
- -H > W
 - Delay due to larger edge capacitance
 - Cross-talk with neighboring wires
 - Permutation of signal wires
 - Interleaving with power and ground wires
- Clock distribution
- Heat dissipation



- ...

Performance

 Microprocessor performance and clock frequency



Power Consumption

- Why low power?
 - High performance and integrity of VLSI circuits
 - Popularity of portable devices
- Power consumption in CMOS circuits
 - Dynamic power dissipation (dominant)
 - Short-circuit power dissipation
 - Leakage power dissipation
- Dynamic power dissipation

$$P_{dynamic} = \alpha \cdot C_{phy} \cdot V_{dd}^2 \cdot f_{clk}$$

where

 α : switching activity

 C_{phy} : physical capacitance

 V_{dd} : supply voltage

 f_{clk} : clock frequency

- Supply voltage reduction
 - Quadratic effect of voltage scaling on power

$$P_{dynamic} = \alpha \cdot C_{phy} \cdot V_{dd}^2 \cdot f_{clk}$$

5V --> 3.3V => 60% power reduction

– Supply voltage reduction => increased latency



System-On-Chip

• Example



- IP/Platform-Based Design
 - Complexity vs. productivity



Reuse of IPs



- IP-based design



- Platform-based design



Hardware Design

- Initial design moves toward more abstract levels as the complexity increases
 - Top-down design with libraries
 - Synthesis tools are used
 - Layout design: layout editor
 - Symbolic layout: layout compactor
 - Gate-level design: technology mapping, P&R
 - RT-level design: Logic synthesis tool
 - Behavioral-level design: Architecture synthesis tool
- Behavioral-level/RTL design using HDL
 - VHDL, Verilog, ...
 - Validation by simulation
 - Refine using synthesis tools
 - Gate-level simulation
 - Placement, routing
 - Circuit/delay extraction, back-annotation
 - Simulation, LVS
 - Emulation, prototyping

• Design flow example



Software Design

- Paradigm shift toward software
 - Microprocessor performance rapidly increases
 - Flexibility, upgradability
 - Low cost
- Microprocessor, microcontroller, DSP, ASIP
- Code optimization in embedded systems
 - Minimization of memory size
 - Maximization of performance
 - Minimization of power consumption
- Estimation of the execution time
 - Worst case performance (hard real-time)
 - Probabilistic performance (soft real-time)
 - Average case performance (no real-time)

Hardware-Software Co-Design

- Benefits of co-design
 - Balancing
 - Performance of customized HW units
 - Programmability of low cost SW components



Reduction of design time



integration

software design

time